

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: SAW FILTER  
MODEL NO 型号: HDBF09024C64 SF6-4  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: 2008-12-18

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. SCOPE

This specification shall cover the characteristics of SAW filter HD BF09024C64

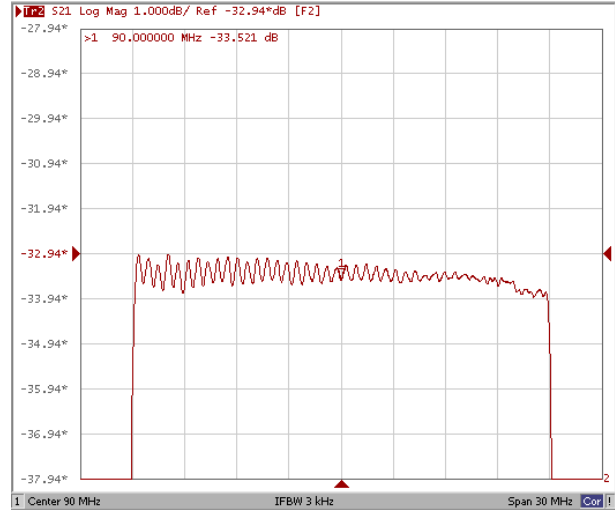
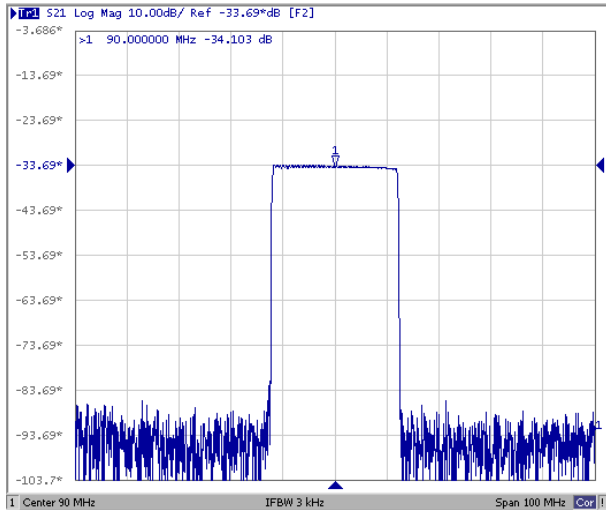
## 2. ELECTRICAL SPECIFICATION

Operation temperature	-40°C to +85°C
Storage temperature	-40°C to +105°C
DC Voltage VDC	0V
Input Power	10dBm Max

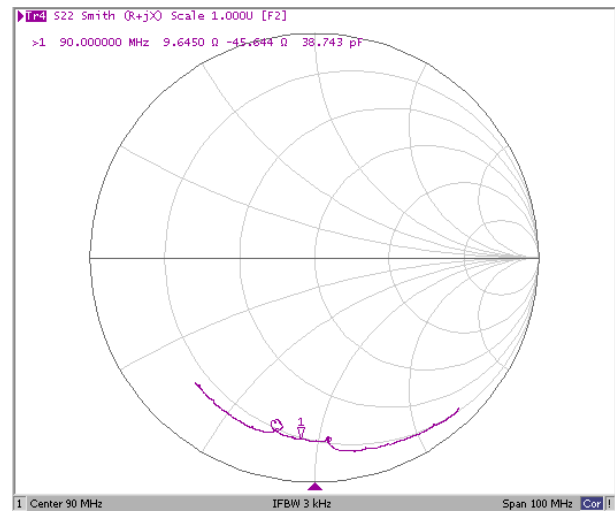
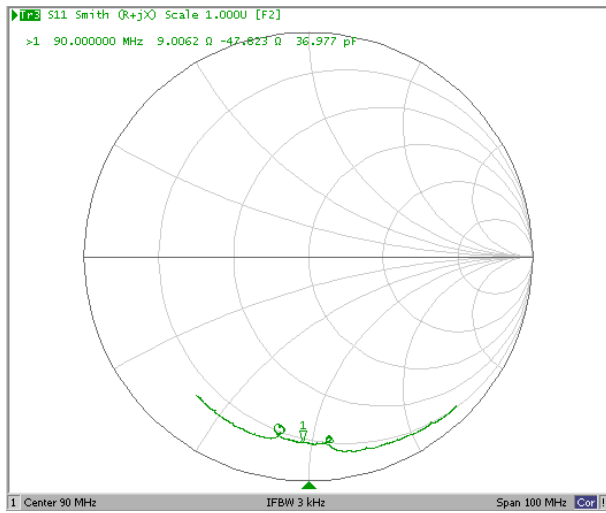
### 2.2 Electronic Characteristics

		Minimum	Typical	Maximum	
Center Frequency	MHz	89.875	90	90.125	
Insertion Loss	dB	-	34	38	
2dB Bandwidth	MHz	24	24.01	-	
3dB Bandwidth	MHz		24.1		
40dB Bandwidth	MHz		24.8		
Passband variation	dB	-	0.9		
Absolute delay	us	-	3.93	4	
Ultimate rejection	F0 ± 12.4MHz	dB	25	28	-
	F0 ± 12.6MHz	dB	40	53	
	F0 ± 13.0MHz	dB	50	53	
	F0 ± 17.0MHz	dB	50	53	
Material Temperature coefficient	KHz/°C		-8.46		
Ambient temperature	°C		25		

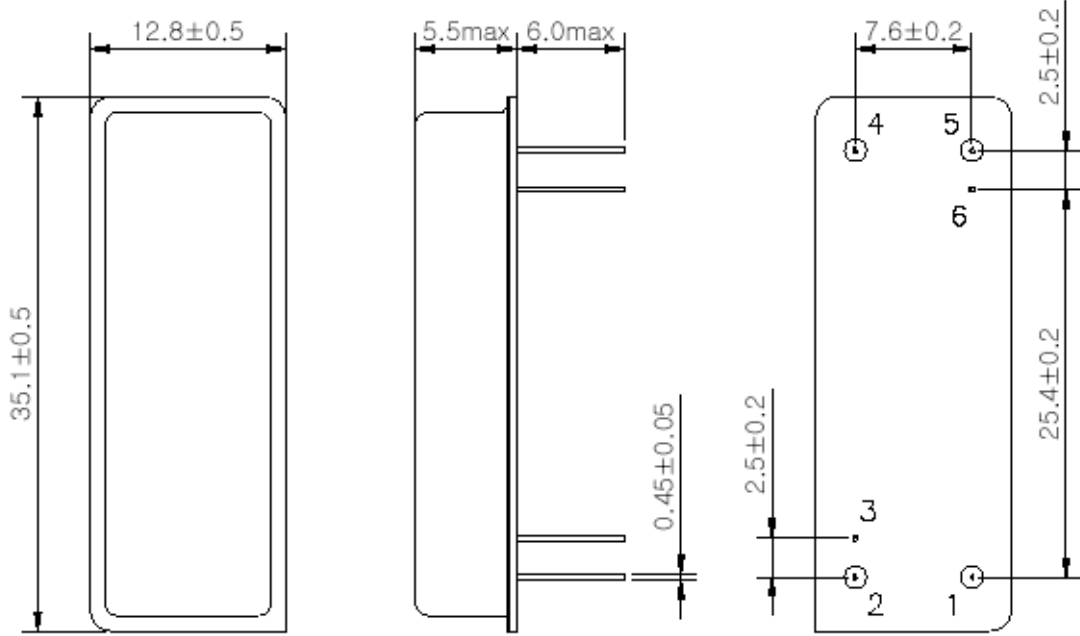
**Typical frequency response**



**Smith Chart**

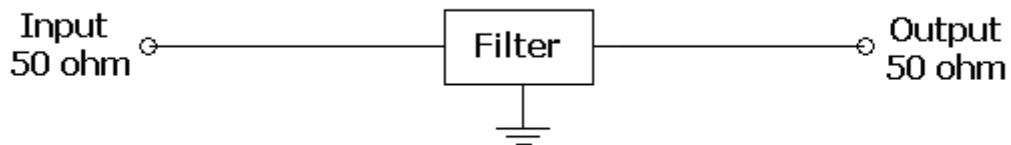


**3. DIMENSION**



Pin Configuration	
1	Input
5	Output
2, 4	Ground
Other	Case ground

**4. TEST CIRCUIT**



## **5. ENVIRONMENTAL CHARACTERISTICS**

### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

### 5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C  $\pm$ 10°C for 10 $\pm$ 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

### 5-5 Solderability

Subject the device terminals into the solder bath at 245°C  $\pm$ 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

## **6. REMARK**

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.